

# Powder Injection Moulding of Multi-Material Devices

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- **Two-component-PIM**
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## Driving Forces for Multi-Material PIM

<b>Economical Objectives</b>	<b>Technological Objectives</b>
<b>create high value-add products</b>	<b>create innovative products with properties profile</b>
<b>reduction of assembly expenditure</b>	
<b>low costs in large and medium series production</b>	
<b>equipment based on established 2C-machinery</b>	

# Multimaterial Devices

## => Multifunctional Products

with **complimentary** or **contradictionary properties**, e.g.

**conductive**

↔

**insulating**

**hard**

↔

**tough**

**magnetic**

↔

**non-magnetic**

**hydrophilic**

↔

**hydrophobic**

**dense**

↔

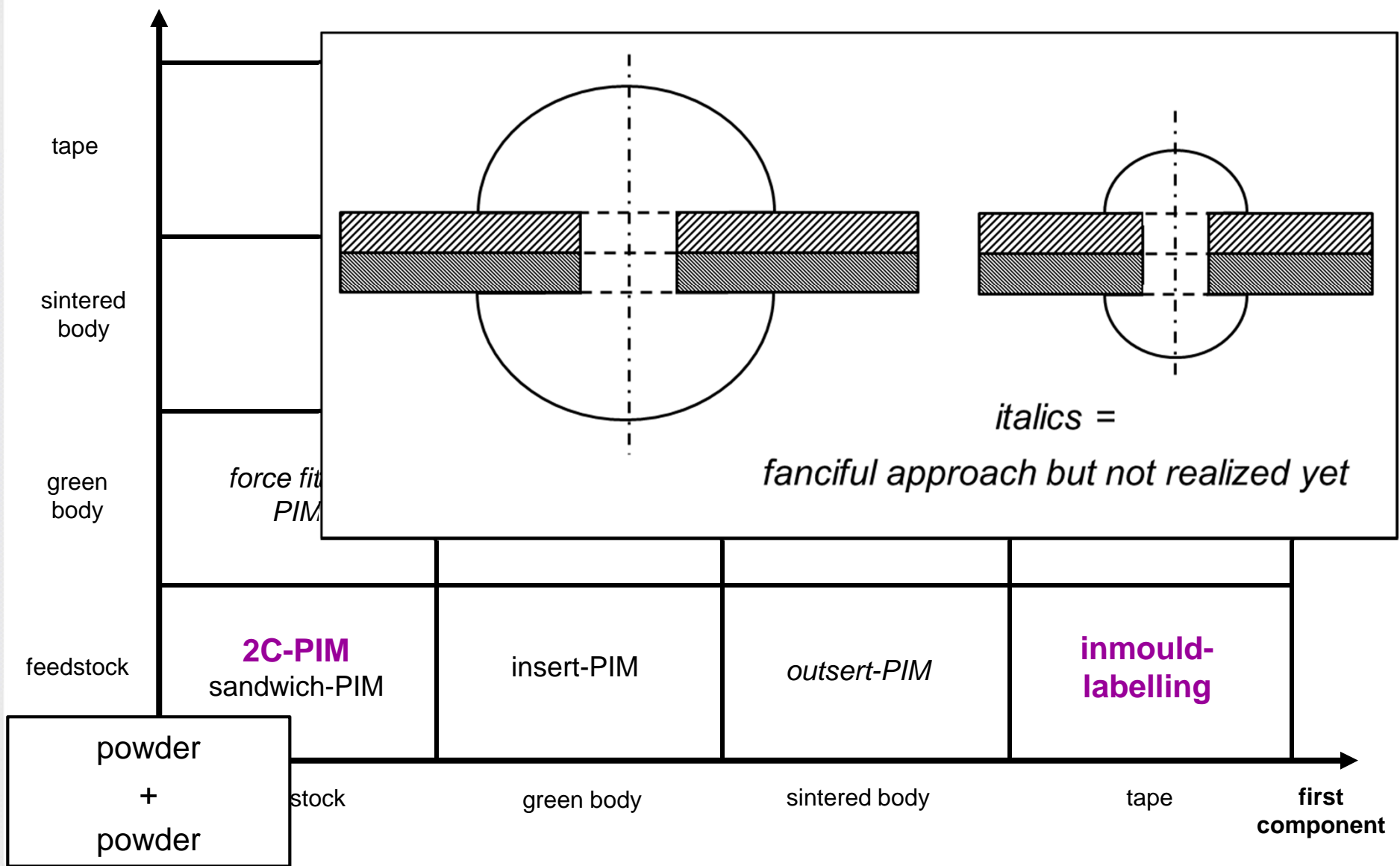
**porous**

**etc.**

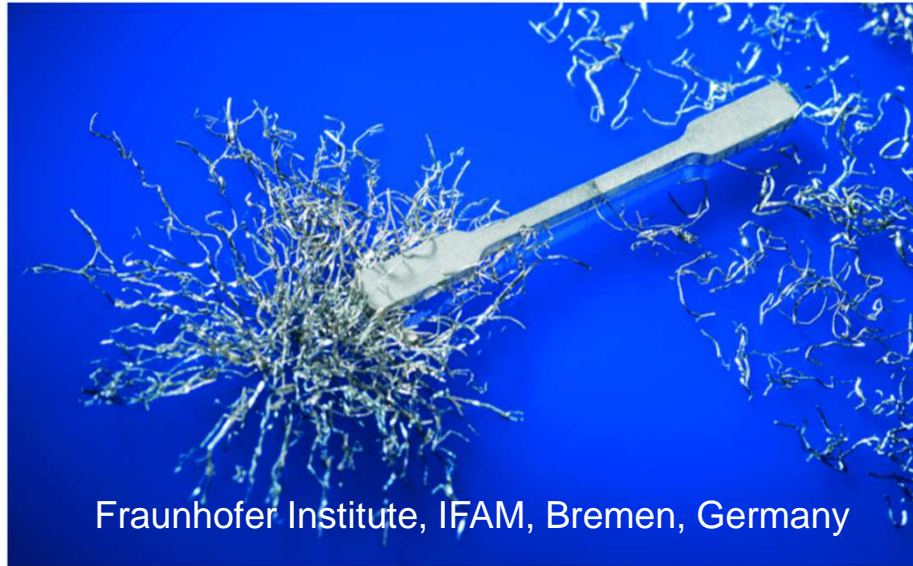
## Driving Forces for Multi-Material PIM

<b>Economical Objectives</b>	<b>Technological Objectives</b>
<b>create high value-add products</b>	<b>create innovative products with properties profile</b>
<b>reduction of assembly expenditure</b>	<b>strong and tight material connections</b>
<b>low costs in large and medium series production</b>	<b>several sub-variants of basic process</b>
<b>equipment based on established 2C-machinery</b>	

# Multi-Material PIM



# 2-Component PIM (Overmoulding)



Fraunhofer Institute, IFAM, Bremen, Germany

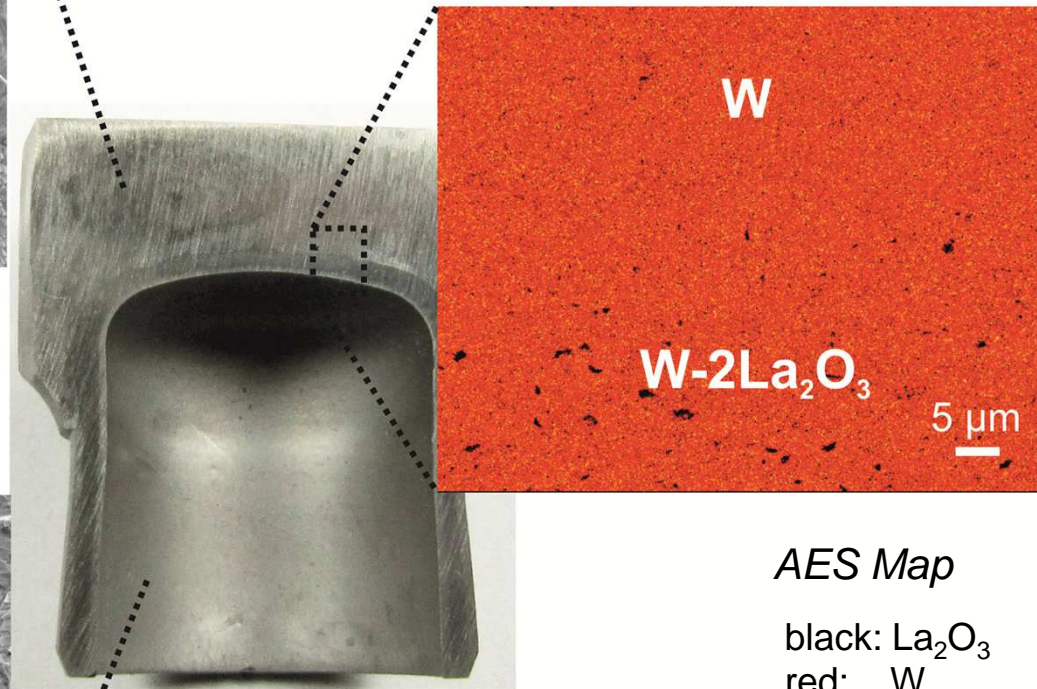
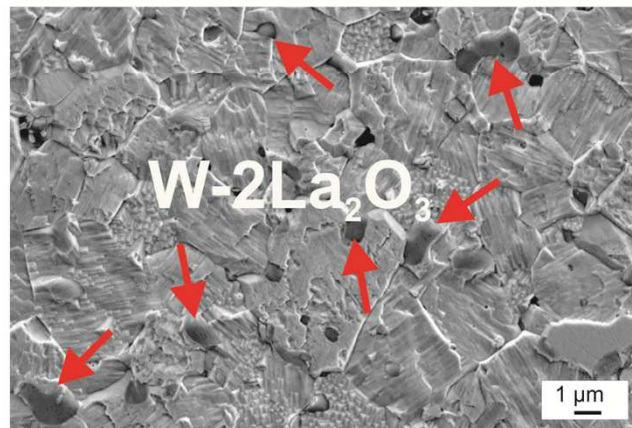
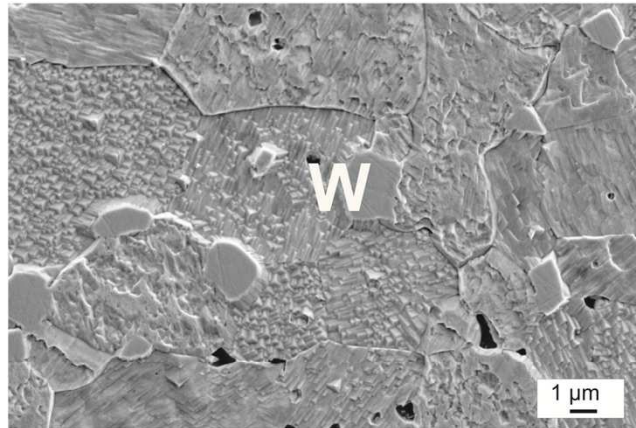
Combination of a magnetic steel (17-4PH) with a non-magnetic steel (316L)

Hard metal WCxCo with different  
Co-contents (16% and 6%)  
ARBURG



2-Component MIM, steel  
AMT, Singapore

# 2-Component Tungsten PIM (2C-WPIM)



AES Map

black:  $\text{La}_2\text{O}_3$

red: W

*Only presintering!*

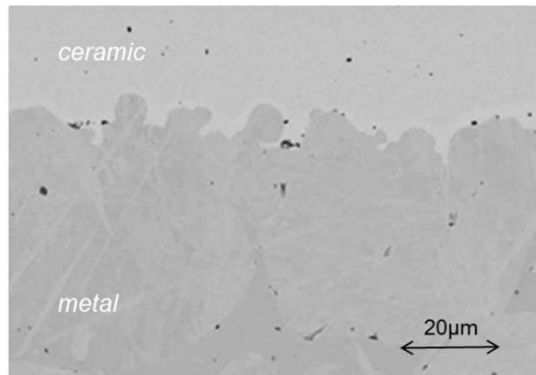


# Combine different Material Classes

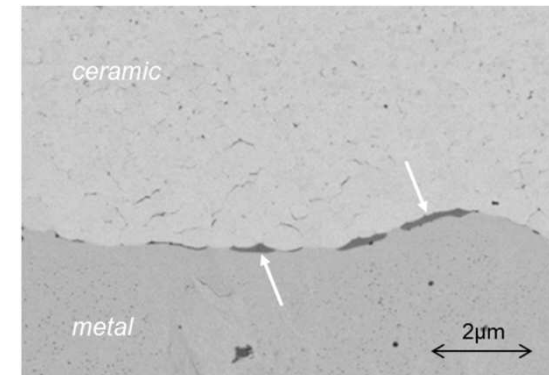
Fixed connection of metal (steel 430L) and ceramic ( $ZrO_2$ )



BSEM images of the interface of ceramic ( $ZrO_2$ ) and metal (steel 17-4PH) samples  
*Courtesy of Fraunhofer Institute IKTS, Dresden, Germany*

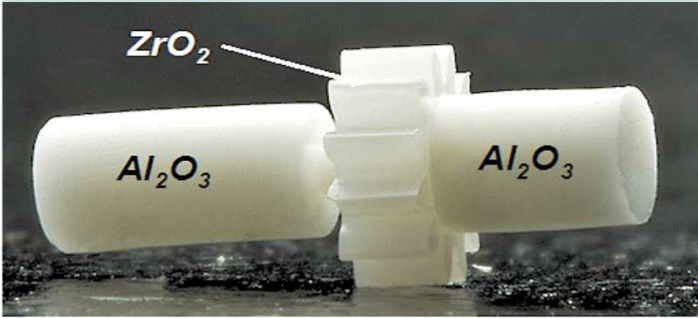
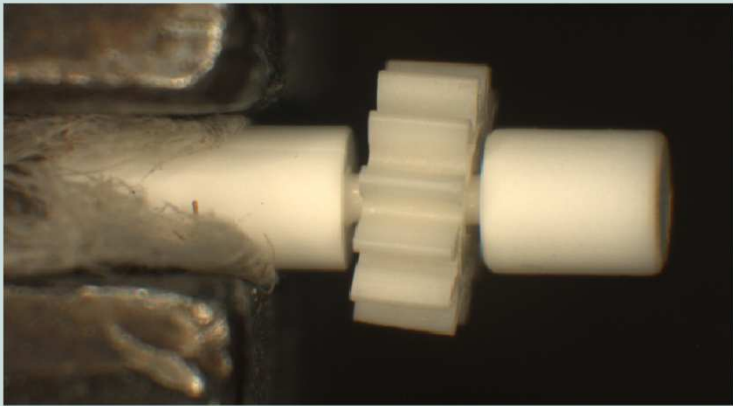


microscopic interlocking structure supported by a partial material bond



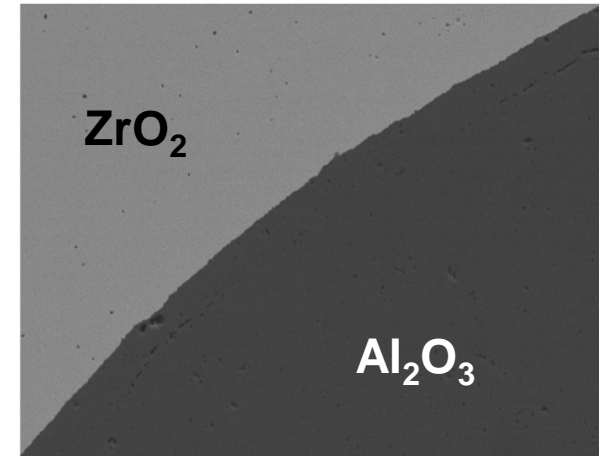
intermediate phase can be detected (white arrows)

# Assembly Powder Injection Moulding

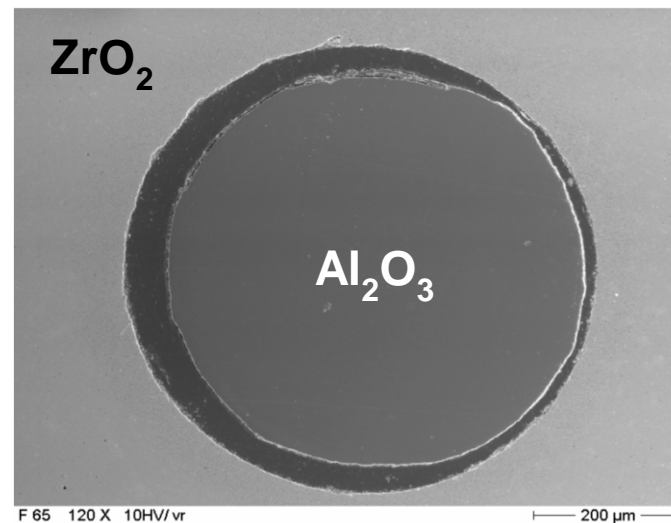
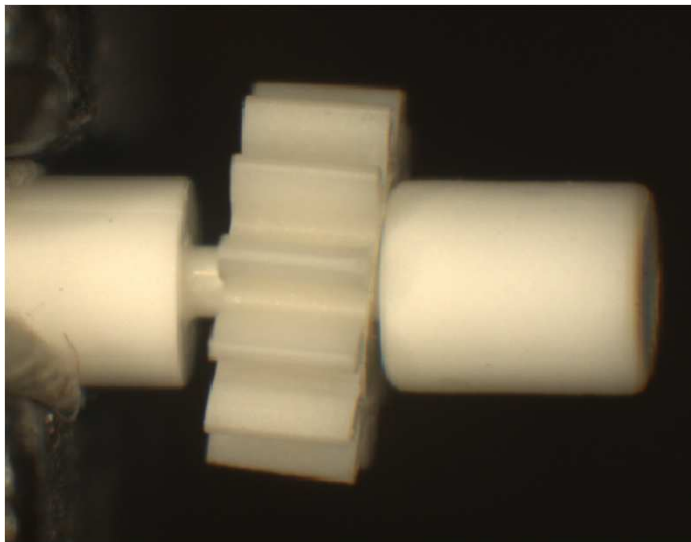
connection	fixed	movable
binders	compatible	not relevant
powder loading	nearly equal	$\varphi_{\text{outside}} > \varphi_{\text{inside}}$
sintering-T	nearly equal	$T_{\text{outside}} > T_{\text{inside}}$
CTE	nearly equal	nearly equal
		

# Assembly Powder Injection Moulding

**Fixed** connections of different ceramics

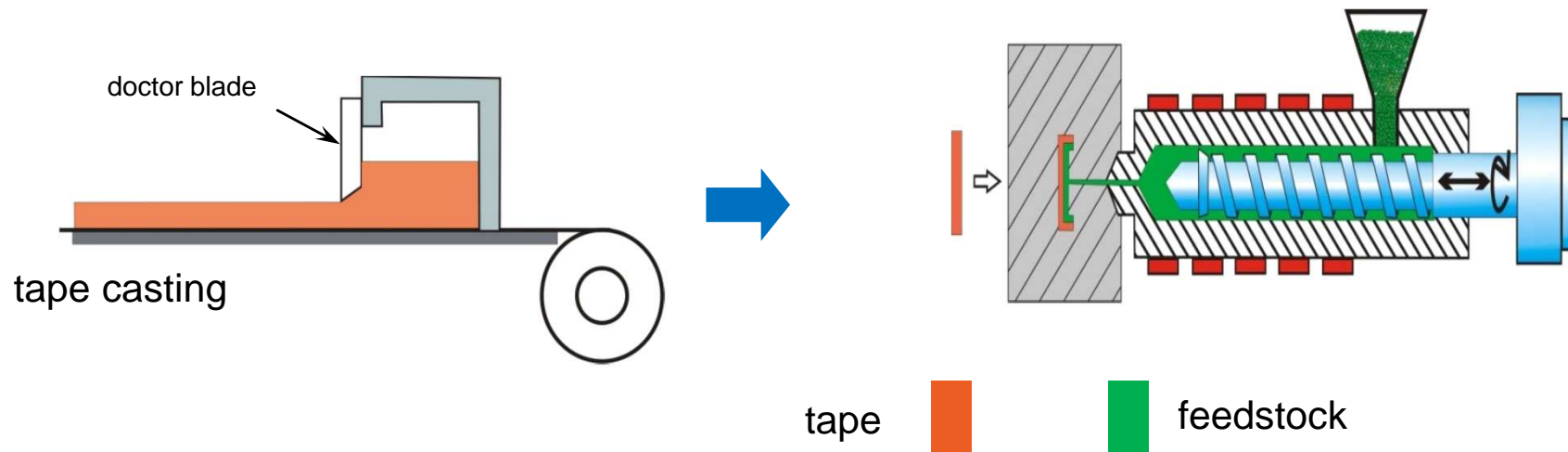


Realisation of  
**movable** connections



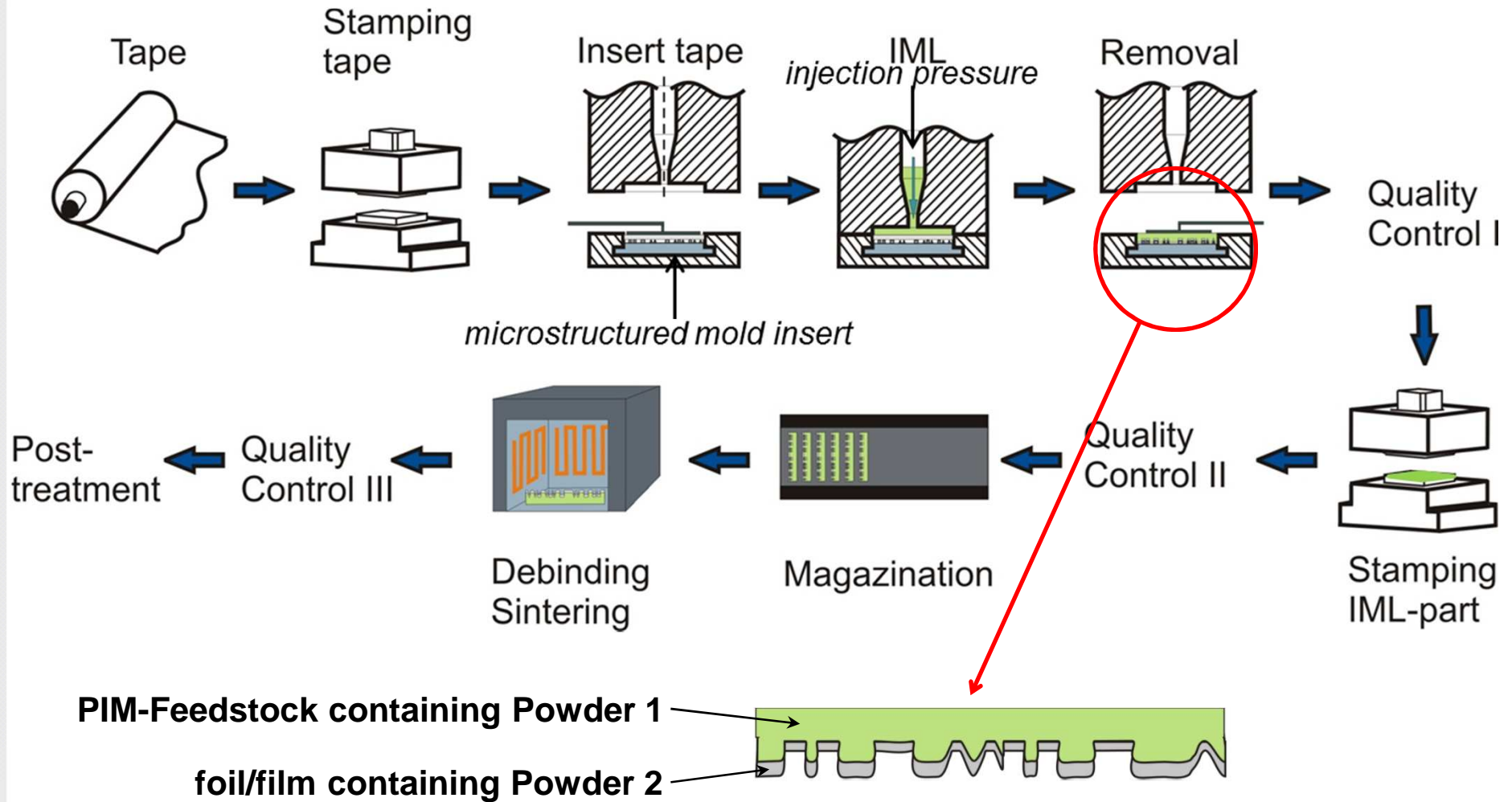
# PIM green bodies + non-PIM green bodies

## Powder Inmould-labelling (IML-PIM)



EU Project No. FP7-NMP4-2007-214122

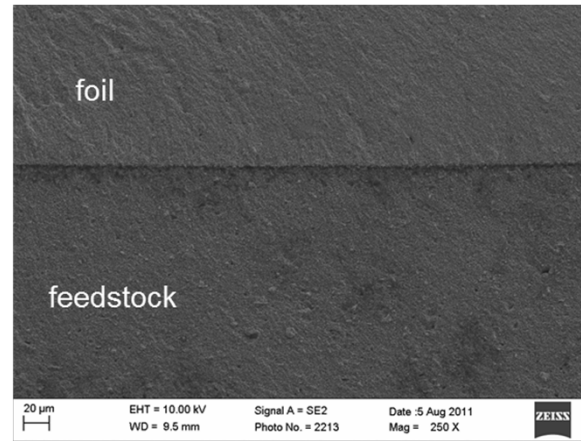
# Micro Powder Inmould-labelling



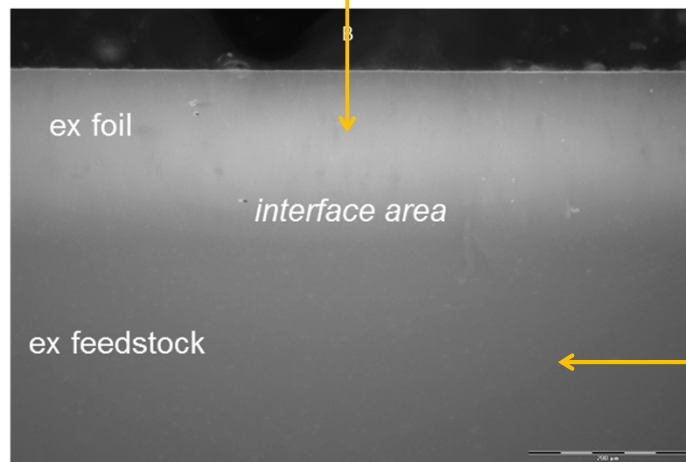
**Powder 2: functional or nano-particles applied on the structured surface**

# Investigation of samples

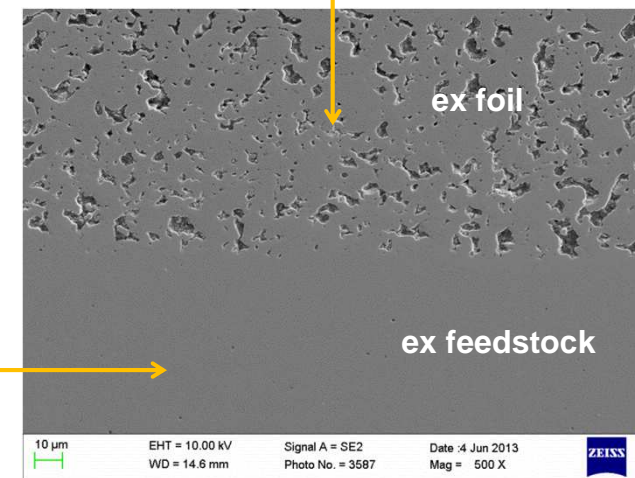
green body



ca. 53Vol% ZrO<sub>2</sub>  
70nm



ca. 50Vol% ZrO<sub>2</sub>  
40nm



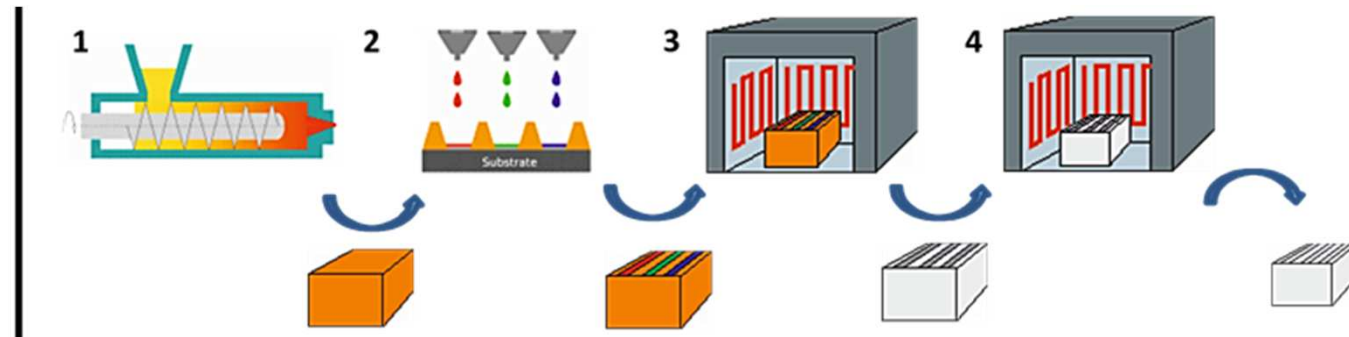
ca. 50Vol% ZrO<sub>2</sub>  
440nm

# Hybrid Process Combinations

## PIM green bodies + non-moulded materials

### PIM + Additive Manufacturing

1. Micro PIM
2. 3D inkjet printing
3. Debinding
4. Sintering



Combining the advantages of

**PIM (high throughput) + AM (customized complex parts)**

# Summary and Outlook

- **Benefits of Multi-Material PIM**  
economical and technological
- **Possibilities of Process Combinations**  
ideas and realized approaches
- **Examples for Material Combinations**  
2C-WPIM, metal/ceramic joints
- **Current focus on Two-component PIM**  
inmould-labelling PIM



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